

V3 Compact Batch Immersion System

System Overview

V3 Compact Batch Immersion System offering either dry-to-dry or dry-to-wet processing with low exhaust requirements, few facility connections and easy maintenance access, while maintaining as much as a 20 percent footprint reduction over comparable tool sets. The V3 robot is designed to accommodate 150 mm or 200 mm wafers in standard cassettes for IC devices; alternate cassettes allow other materials to be processed using the standard robot arm. Suitable for R&D labs and applications.

Substrate Size:	150 mm, 200 mm
Applicable material:	Silicon, SiC, Glass, Sapphire (LED)
Technology Markets:	Analog IC, Power IC, MEMS, R&D

Processes

- RCA Clean
- Oxide Etch

Production Advantages

- V3 uses the same subsystems as our highly reliable GAMA Series product line
- Easy access serviceability
- Upgradeable and reconfigurable as your needs change
- Multiple chemistry support, processes/recipes and flexible configurations

